



VERSION OF CLAIMS WITH MARKINGS

2. (Amended) The process of Claim 1 [wherein the heat sink is fabricated] further comprising fabricating the heat sink from a metal alloy having precipitating constituents.

4. (Amended) The process of Claim 1 [wherein the heat sink is part of] further comprising affixing the heat sink to a microelectronic package including a die affixed to a carrier substrate.

13. (Amended) The process of Claim 8 [wherein the heat sink is fabricated] further comprising fabricating the heat sink from an aluminum alloy.

14. (Amended) The process of Claim 8 [wherein the heat sink is fabricated] further comprising fabricating the heat sink from a copper alloy.

16. (Amended) The process of Claim 14 [wherein the heat sink is fabricated] further comprising fabricating the heat sink from a metal alloy with secondary recrystallization grain growth.

18. (Amended) The process of Claim 14 [wherein the heat sink is part of] further comprising affixing the heat sink to a microelectronic package which includes a die [affixed] coupled to a package substrate, the thermal conductivity of the heat sink improved by reducing the grain boundaries that obstruct the movement of atomic and molecular species.

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